TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

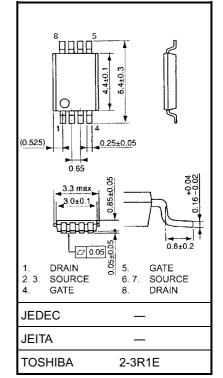
# T P C S 8 2 1 2

Lithium Ion Battery Applications

- Has a small footprint.
- Low drain-source ON resistance:  $RDS(ON) = 16 m\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 11 \text{ S (typ.)}$
- Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 20 \ V)$
- Enhancement-mode:  $V_{th}$  = 0.5~1.2 V (V\_{DS} = 10 V, I\_D = 200  $\mu A)$
- Common drain

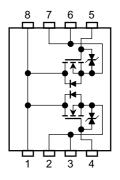
### Maximum Ratings (Ta = 25°C)

Char	acteristics	Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	20	V	
Drain-gate voltag	ge (R <sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	20	V	
Gate-source voltage		V <sub>GSS</sub>	±12	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	6	А	
Drain current	Pulse (Note 1)	I <sub>DP</sub>	24	A	
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D (1)</sub>	1.1		
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.75	W	
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	0.6	vv	
	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.35		
Single pulse avalanche energy (Note 4)		E <sub>AS</sub>	46.8	mJ	
Avalanche curre	nt	I <sub>AR</sub>	6	А	
Repetitive avalar Single-device va	nche energy lue at dual operation (Note 2a, 3b, 5)	E <sub>AR</sub>	0.075	mJ	
Channel tempera	ature	T <sub>ch</sub>	150	°C	
Storage tempera	ture range	T <sub>stg</sub>	-55~150	°C	



Weight: 0.035 g (typ.)

# **Circuit Configuration**



Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5) Please see next page.

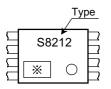
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm

# **Thermal Characteristics**

Characteristics	Symbol	Max	Unit		
Thermal resistance, channel to ambier	Single-device operation (Note 3a)	R <sub>th (ch-a)</sub> (1)	114		
(t = 10  s) (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	167	°C/W	
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	208		
(t = 10  s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	357	°C/W	

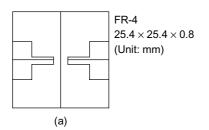
# Marking (Note 6)



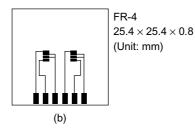
Note 1: The channel temperature should not exceed 150°C.

Note 2:

a) Device mounted on a glass-epoxy board (a)



b) Device mounted on a glass-epoxy board (b)



#### Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).

Note 4:  $V_{DD} = 16 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 1.0 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 6 A

- Note 5: Repetitive rating; pulse width limited by max channel temperature.
- Note 6: on lower right of the marking indicates Pin 1.
  \* shows lot number. (Year of manufacture: last decimal digit of the year of manufacture, Month of manufacture: January to December are denoted by letters A to L respectively)

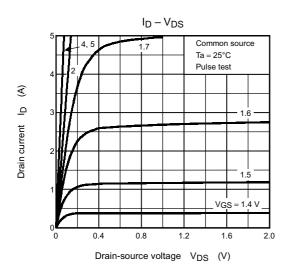
Electrical Characteristics (Ta = 25°C)

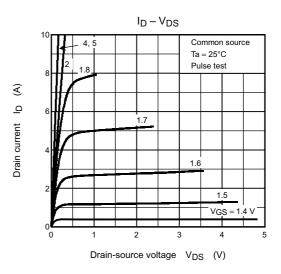
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS}=\pm 10~V,~V_{DS}=0~V$	—		±10	μA
Drain cut-OFF current		I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_	—	10	μA
Drain-source breakdown voltage		V (BR) DSS		20	—		V
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	8	—		v
Gate threshold ve	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 200 \ \mu\text{A}$	0.5	—	1.2	V
Drain-source ON resistance			$V_{GS} = 2.0 \text{ V}, I_D = 4.2 \text{ A}$	_	26	45	mΩ
		R <sub>DS (ON)</sub>	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 4.2 \text{ A}$	_	21	29	
			$V_{GS} = 4.0 \text{ V}, \text{ I}_{D} = 4.8 \text{ A}$	_	16	24	
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 3.0 \text{ A}$	5.5	11	_	S
Input capacitance	Э	C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	1590	_	pF
Reverse transfer	capacitance	C <sub>rss</sub>			180		
Output capacitan	ce	C <sub>oss</sub>		_	200	_	
Switching time	Rise time	tr	$V_{GS} \begin{array}{c} 5 \\ 0 \\ V \end{array} \begin{array}{c} V_{GS} \\ 0 \\ V \end{array} \begin{array}{c} V \\ 0 \\ 0$	_	6.4	_	
	Turn-ON time	t <sub>on</sub>			22		• ns
	Fall time	t <sub>f</sub>			10		
	Turn-OFF time	t <sub>off</sub>			42		
Total gate charge (gate-source plus gate-drain)		Qg			20		
Gate-source charge 1		Q <sub>gs1</sub>	$V_{DD} \simeq 16 \text{ V}, \text{ V}_{GS} = 5 \text{ V}, \text{ I}_{D} = 6 \text{ A}$	_	3.5	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>		_	4.5	_	

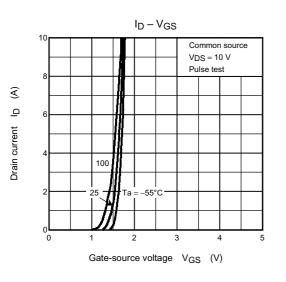
# Source-Drain Diode Ratings and Characteristics (Ta = 25°C)

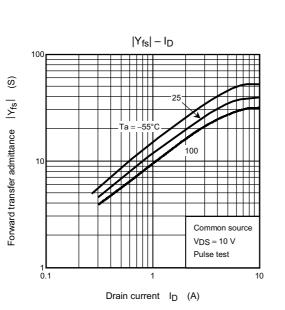
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	24	Α
Diode forward voltage		V <sub>DSF</sub>	$I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V}$			-1.2	V

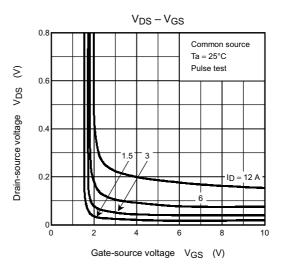
# **TOSHIBA**

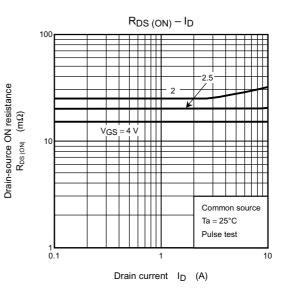




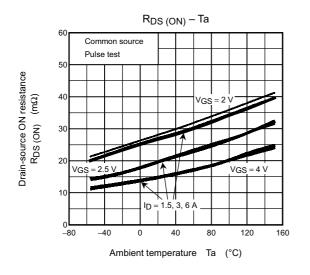


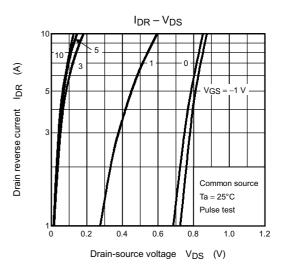


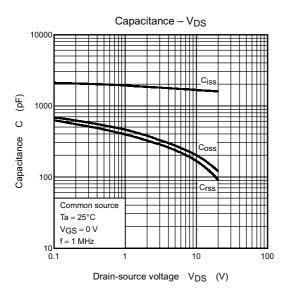


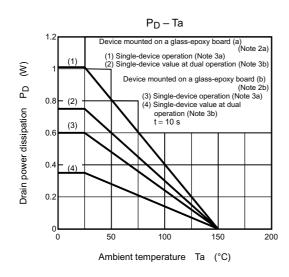


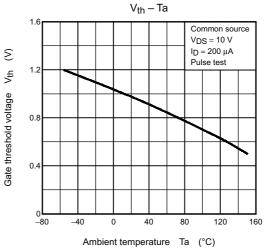
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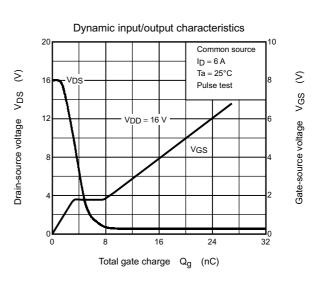


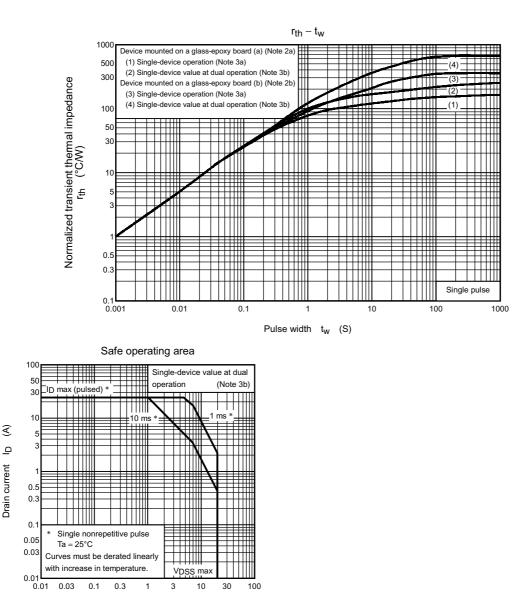












Drain-source voltage  $V_{DS}$  (V)

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